



GaAs Family: Photocathode Design

Godparent Review 2/26/2010



Overview

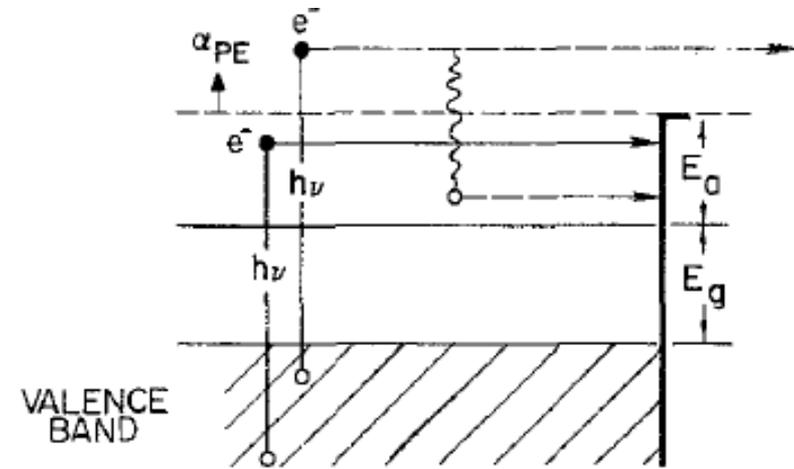
- Goals
- What is a photocathode?
- Wavelength Optimization
- Doping Profile
- Emission Properties
- Transfer Process
- Bonding
- Conclusion



Goals

- Wavelength optimization
- Quantum efficiency larger 20% in average with small batch-to-batch variation
- Reduction of dark-current: novel concepts of doping
- Development of cost-efficient large area transfer & bonding method
- All growth & bonding processes fully industrial compatible (foundry)

What is a photocathode?

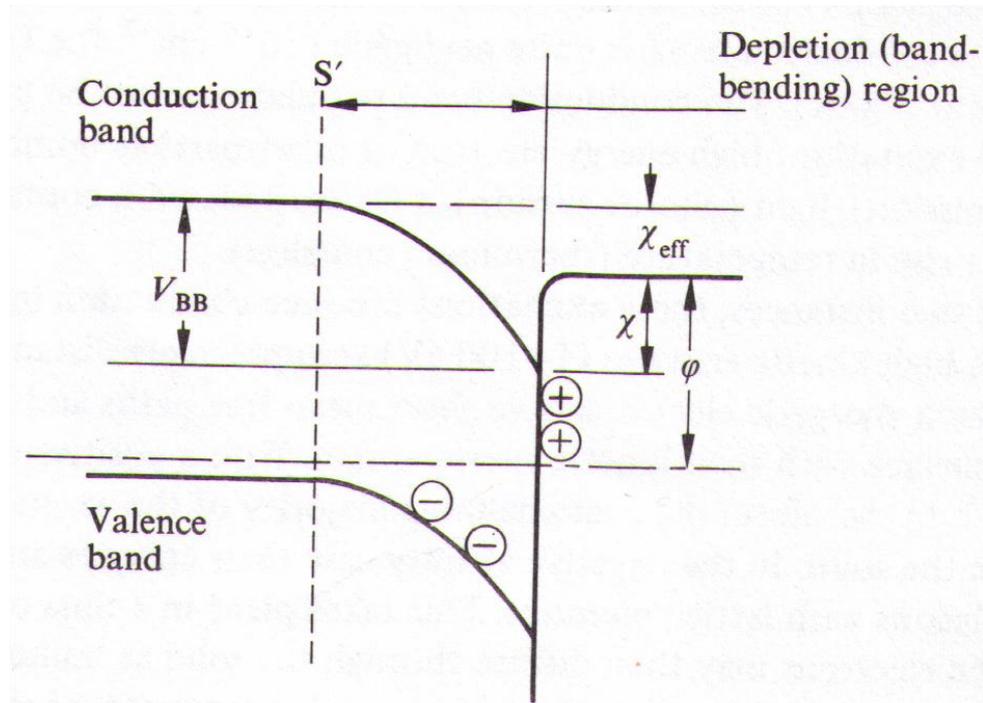


$$Y = \frac{\alpha_{PE}}{\alpha} \times \frac{1}{1 + \lambda \alpha / L} \times P$$

PROBABILITY OF BEING EXCITED WITH SUFFICIENT ENERGY TO ESCAPE

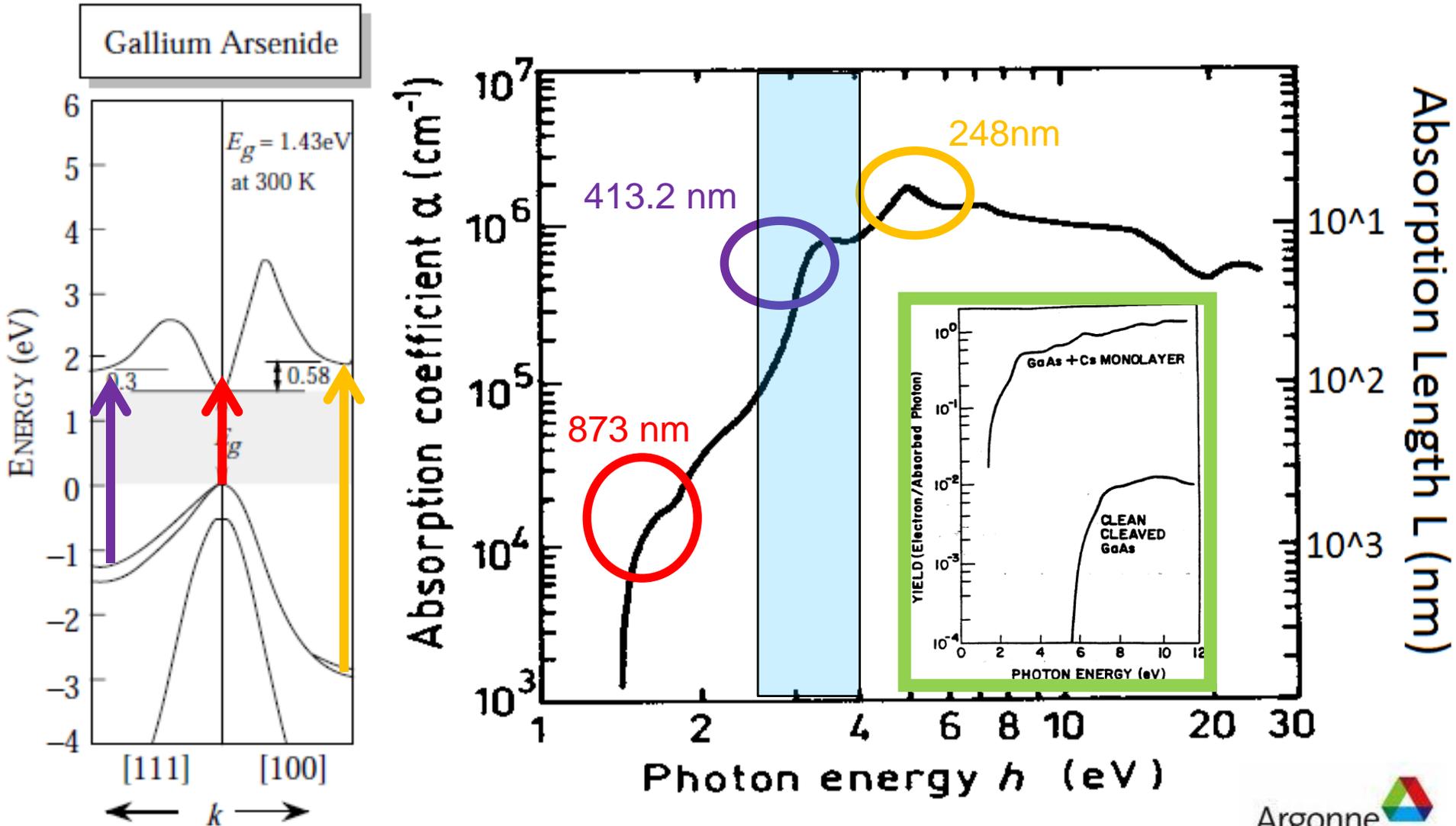
PROBABILITY OF REACHING SURFACE WITH SUFFICIENT ENERGY TO ESCAPE

PROBABILITY OF ESCAPE AFTER REACHING SURFACE



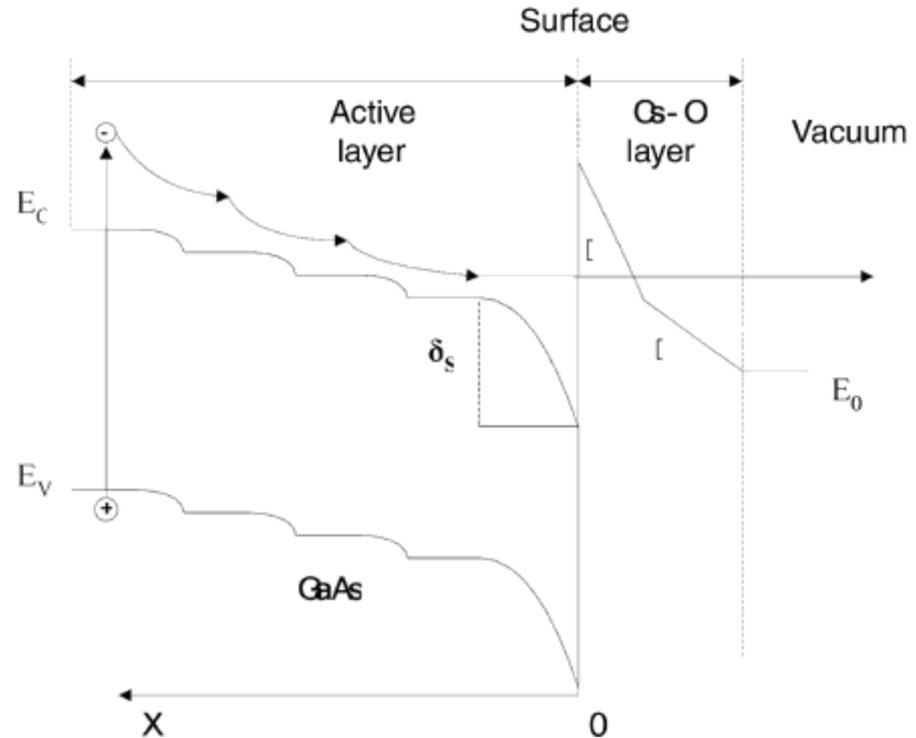
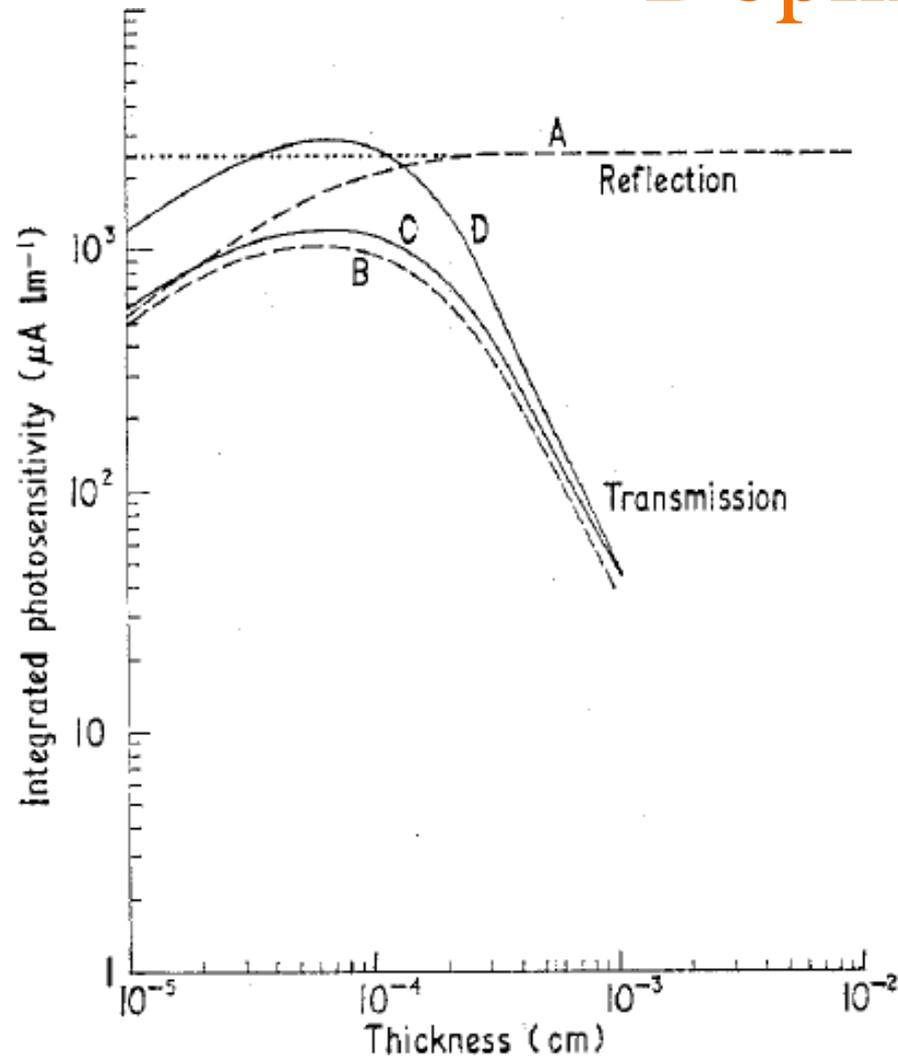


Wavelength Optimization



[1],[3]

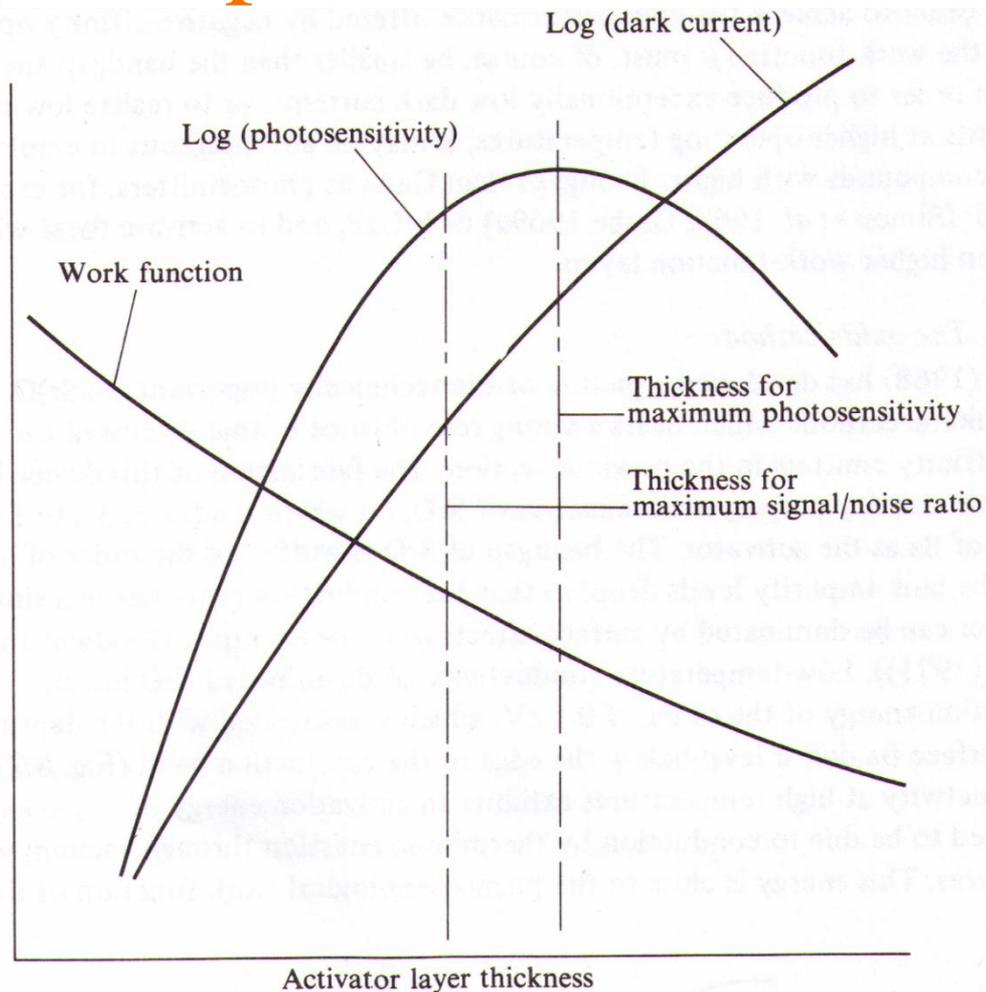
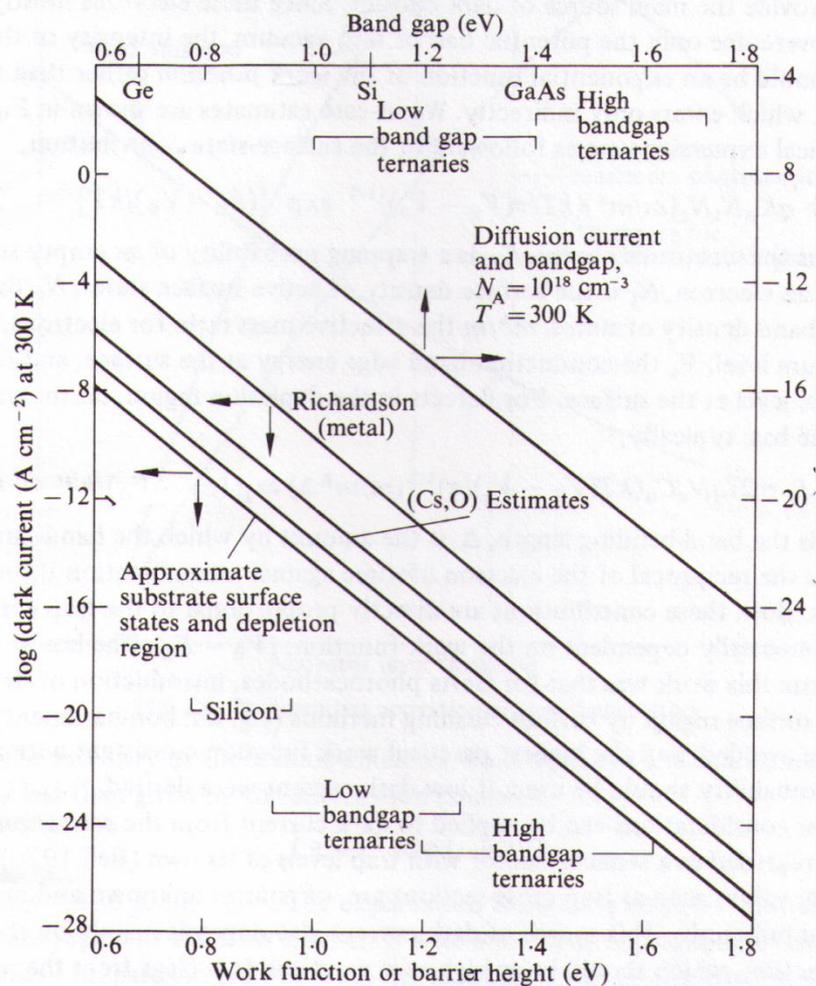
Doping Profile



| | | |
|-----------------------|------------------------------------|-------------|
| 0.25μm | $1 \times 10^{18} \text{ cm}^{-3}$ | ← section 4 |
| 0.25μm | $4 \times 10^{18} \text{ cm}^{-3}$ | ← section 3 |
| 0.25μm | $7 \times 10^{18} \text{ cm}^{-3}$ | ← section 2 |
| 1.85μm | $1 \times 10^{19} \text{ cm}^{-3}$ | ← section 1 |
| p-GaAs(100) substrate | | |

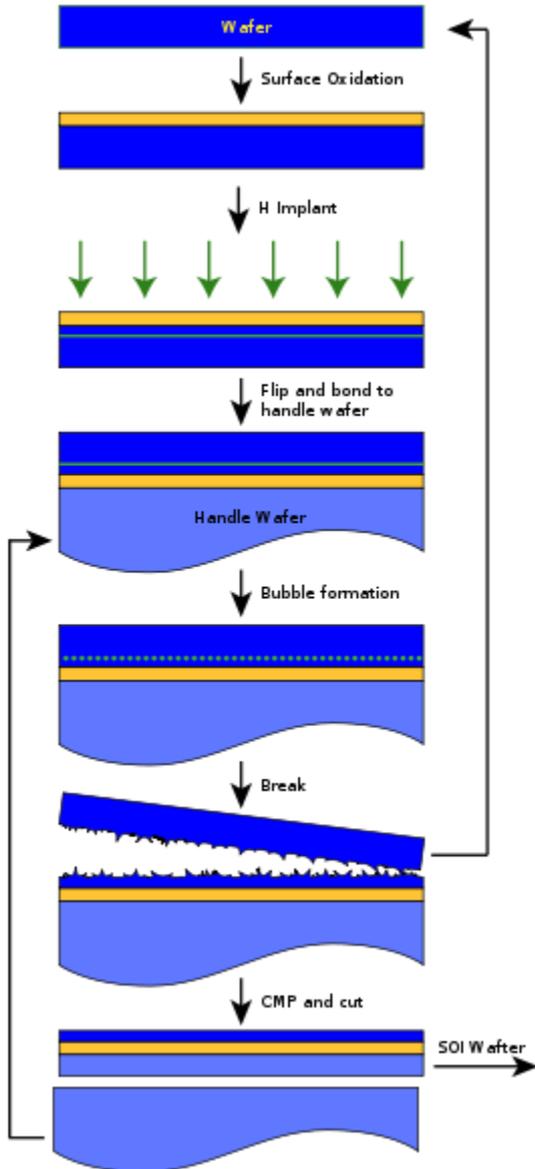


Emission Properties

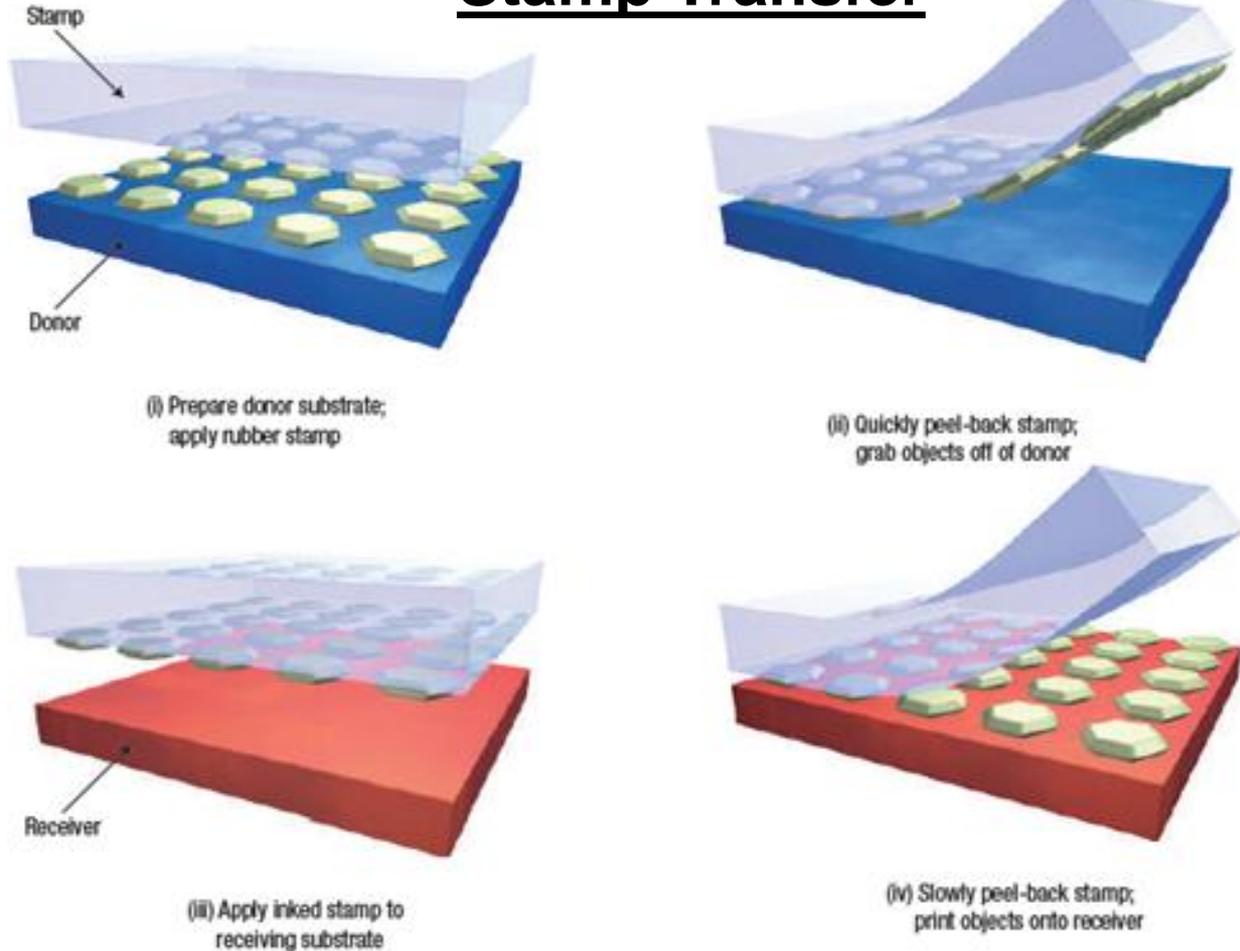


Transfer Process

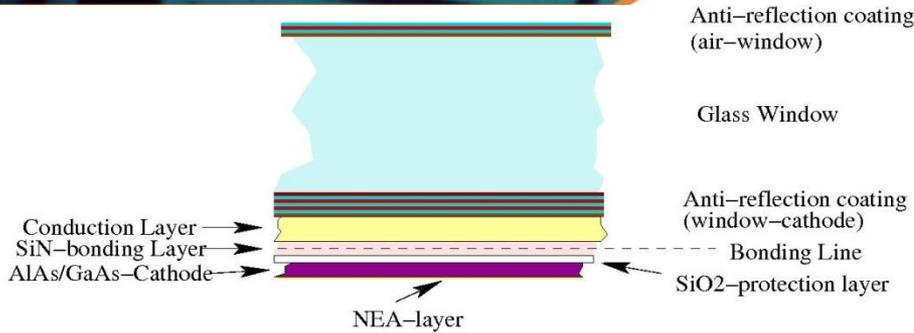
Smart Cut



Stamp Transfer



[6],[7]



- SiN-bonding
 - Developed for 3d integration
 - Low temperature process (maximal temp~400C)
 - About 30nm-60nm thickness
 - Industrially available
- Protection of cathode structure
 - Low temperature
 - Inter-diffusion barrier

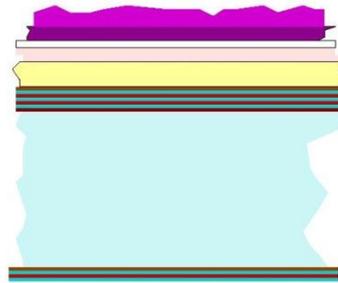
GaAs – Wafer



Smart-cut: first step



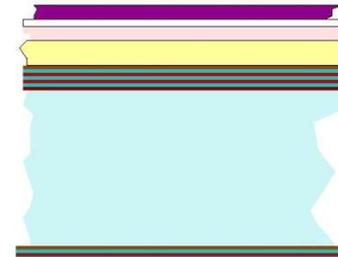
smart cut second step



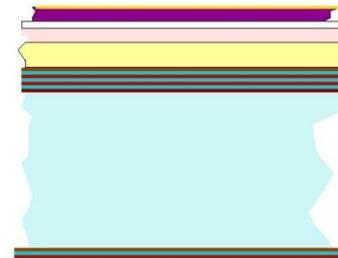
Window material



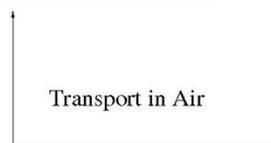
Polishing/Etching



Cleaning & Activation



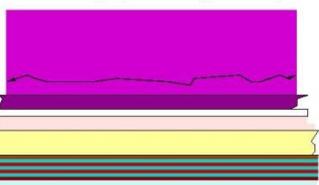
Transport in Air



Growth of structure



Bonding (low temperature)





Conclusion

- GaAs is a suitable material for the proper wavelength
 - III-V system can be alloyed for adjustment
- Doping profile has to maintain a balance between electric field, dark current, recombination rate and quantum efficiency
- Transferring and bonding have to be efficient and repeatable but maintain electrical and structural integrity of the photocathode



References

- [1] W.E. Spicer and A. Herrera-Gomez, “Modern theory and applications of photocathodes,” SPIE MILESTONE SERIES MS, vol. 169, 2001, pp. 104–119.
- [2] R.L. Bell, Negative electron affinity devices, Clarendon Press, Oxford, 1973.
- [3] <http://www.eecs.umich.edu/~singh/bk7ch03.pdf>
- [4] G.A. Allen, “The performance of negative electron affinity photocathodes,” Journal of Physics D: Applied Physics, vol. 4, 1971, pp. 308-317.
- [5] Z. Yi-Jun, C. Ben-Kang, Y. Zhi, N. Jun, and Z. Ji-Jun, “Distribution of carriers in gradient-doping transmission-mode GaAs photocathodes grown by molecular beam epitaxy,” Chinese Physics B, vol. 18, 2009, pp. 4541-4546.
- [6] “Smart Cut - Wikipedia, the free encyclopedia.”
- [7] M.A. Meitl, Z.T. Zhu, V. Kumar, K.J. Lee, X. Feng, Y.Y. Huang, I. Adesida, R.G. Nuzzo, and J.A. Rogers, “Transfer printing by kinetic control of adhesion to an elastomeric stamp,” Nature Materials, vol. 5, 2006, pp. 33–38.